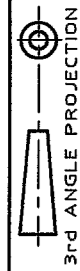


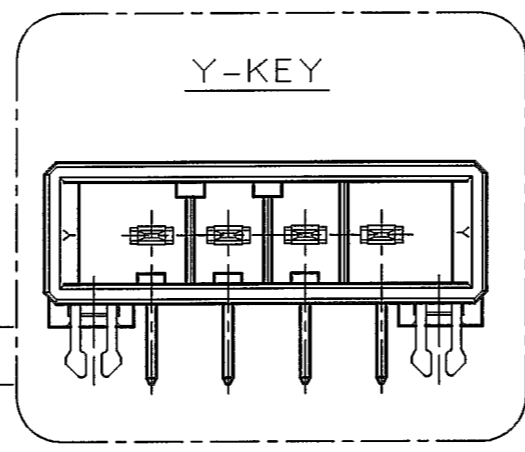
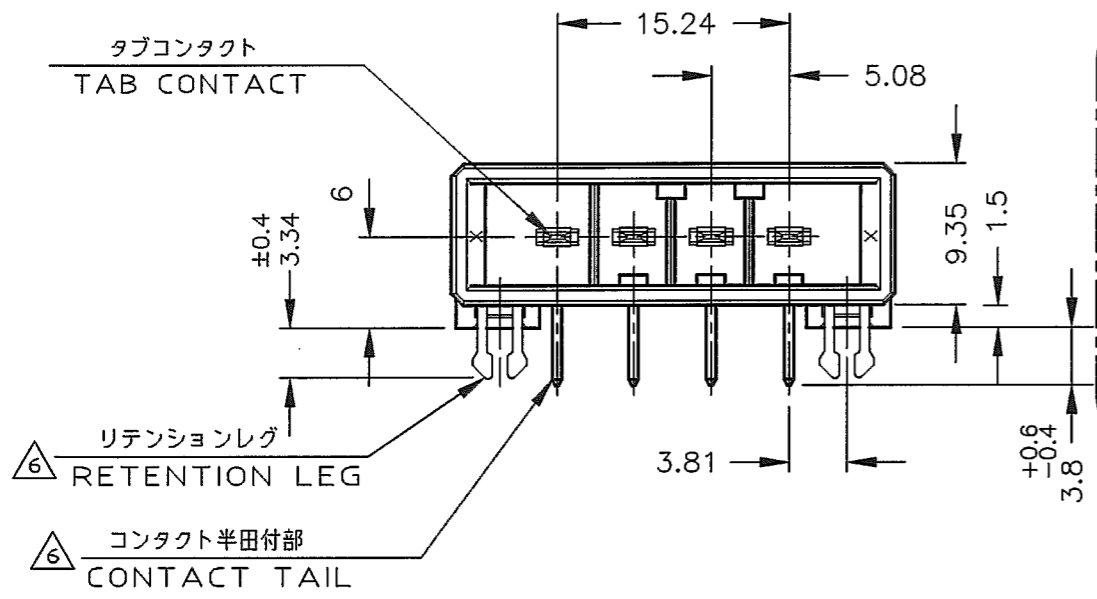
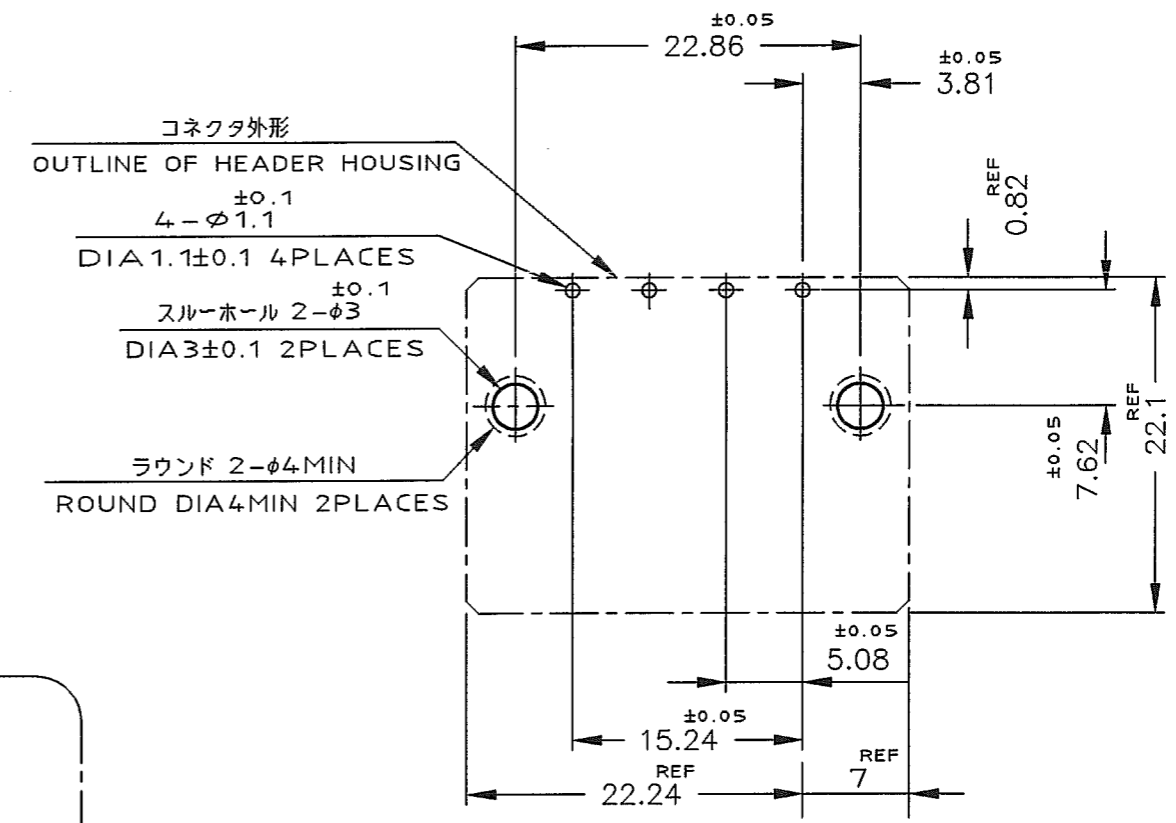
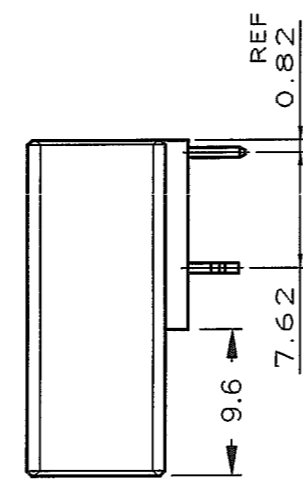
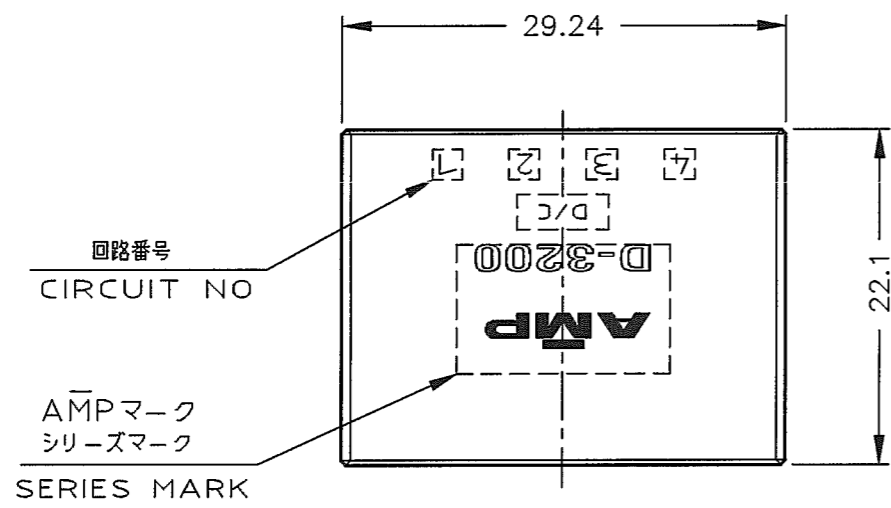
NUMBER 179277



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け穴寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
2. FINISH (CONTACT AREA): 0.38μm PdNi & Au PLATING OVER NICKEL
3. FINISH (CONTACT AREA): 0.76μm PdNi & Au PLATING OVER NICKEL
4. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
5. FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
6. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

△6	△4	2-179277-5	Y
△6	△3	2-179277-3	Y
△6	△2	2-179277-2	Y
△6	△4	1-179277-5	X
△6	△3	1-179277-3	X
△6	△2	1-179277-2	X
(FINISH)	製品番号 (PART NO.)	KEY	

E	REVISED PER ECR-25-250788	F.Z	R.B	16 JAN 2025
D1	REVISED PER ECO-11-005030	RK	HMR	23 MAR 11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA	NAME				
mm ² (AWG -)		mmφ	4 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200				
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	SIZE	LOC	NUMBER
DR. N. Matsubara 10 DEC 93		DE. N. Matsubara 10 DEC 93		10mm以下: ±0.3	A3	J	C-179277
CHK. S. MANABE 13 DEC 93		APP. S. MANABE 13 DEC 93		10mm超 30mm以下: ±0.4	SCALE		REV.
				30mm超 100mm以下: ±0.5	2-1		E
				角 度: ±3'			SHEET
							1 OF 1